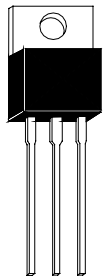
HD44H11

NPN EPITAXIAL PLANAR TRANSISTOR



TO-220

Description

The HD44H11 is designed for various specific and general purpose applications, such as:output and driver stages of amplifiers operating at frequencies from DC to greater than 1MHz; series, shunt and switching regulators; low and high frequency inverters/converters; and many others.

Absolute Maximum Ratings (Ta=25°C)

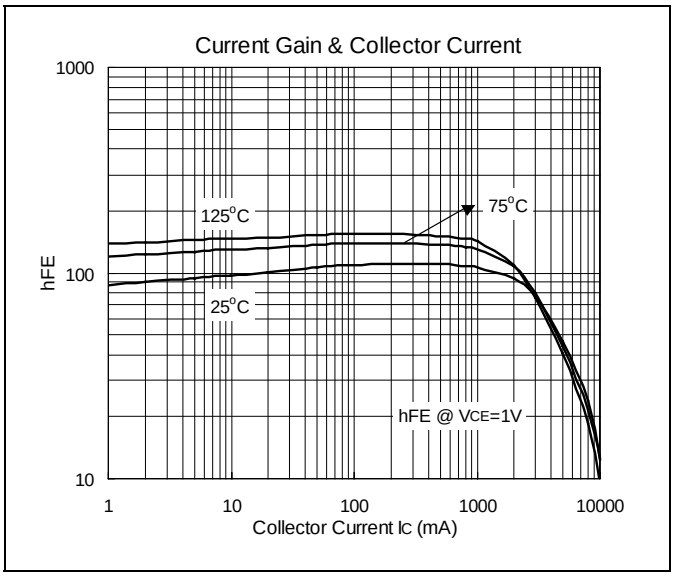
- Maximum Temperatures
  Storage Temperature ..... -55 ~ +150 °C
  Junction Temperature .....+150 °C Maximum
- Maximum Power Dissipation
  Total Power Dissipation (Tc=25°C) ..... 50 W
  Total Power Dissipation (Ta=25°C) ..... 1.67 W
- Maximum Voltages and Currents
  BVCBO Collector to Base Voltage..... 80 V
  BVCEO Collector to Emitter Voltage..... 80 V
  BVEBO Emitter to Base Voltage..... 5 V
  IC Collector Current..... 10 A
  IB Base Current..... 5 A

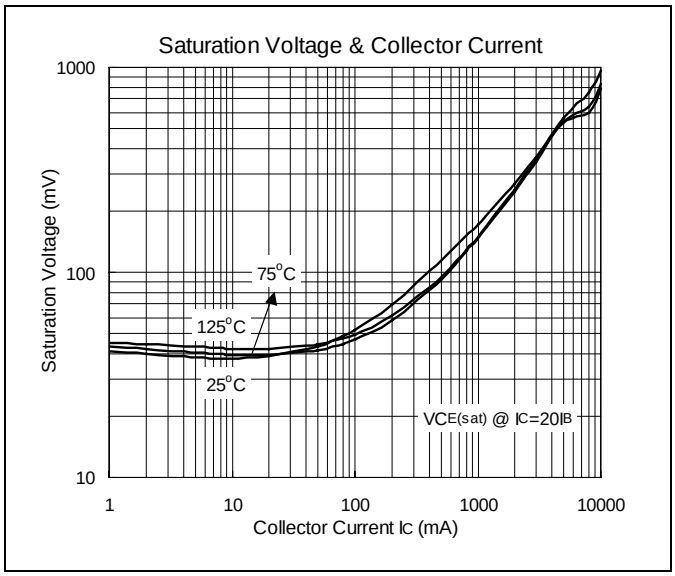
Characteristics (Ta=25°C)

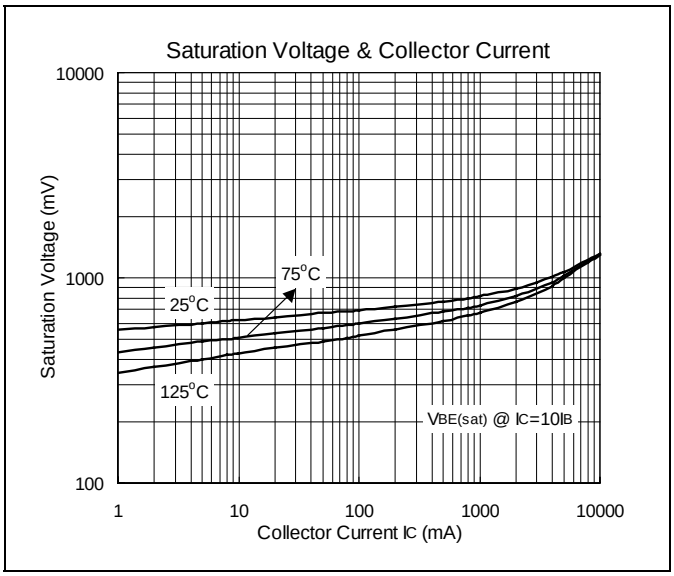
Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	80	-	-	V	IC=100mA, IB=0
BVCEO	80	-	-	V	IC=100mA, IB=0
BVCES	80	-	-	V	IC=1mA, IC=0
BVEBO	5	-	-	V	IE=1mA
ICES	-	-	10	uA	VCE=80V
IEBO	-	-	100	uA	VEB=5V
*VCE(sat)	-	-	1	V	IC=8A, IB=0.4A
*VBE(sat)	-	-	1.5	V	IC=8A, IB=0.8A
*hFE1	60	-	-		IC=2A, VCE=1V
*hFE2	40	-	-		IC=4A, VCE=1V
Cob	-	130	-	pF	VCB=10V
fT	-	50	-	MHz	VCE=1V, IC=500mA, f=100MHz

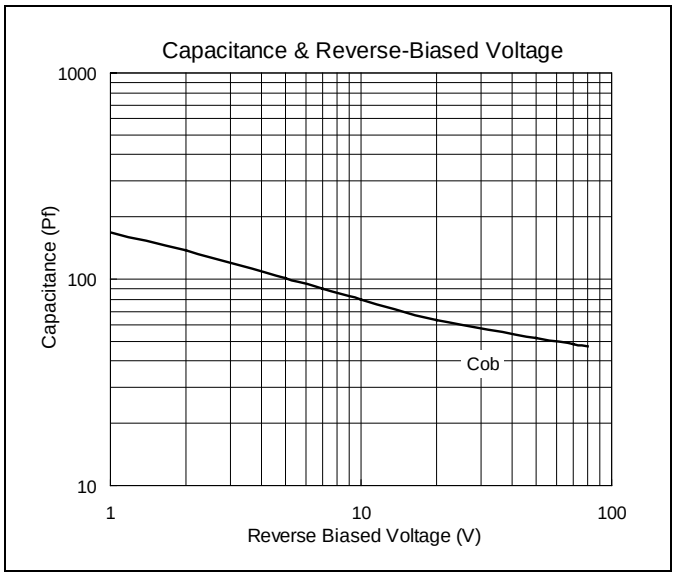
*Pulse Test: Pulse Width ≤380us, Duty Cycle≤2%

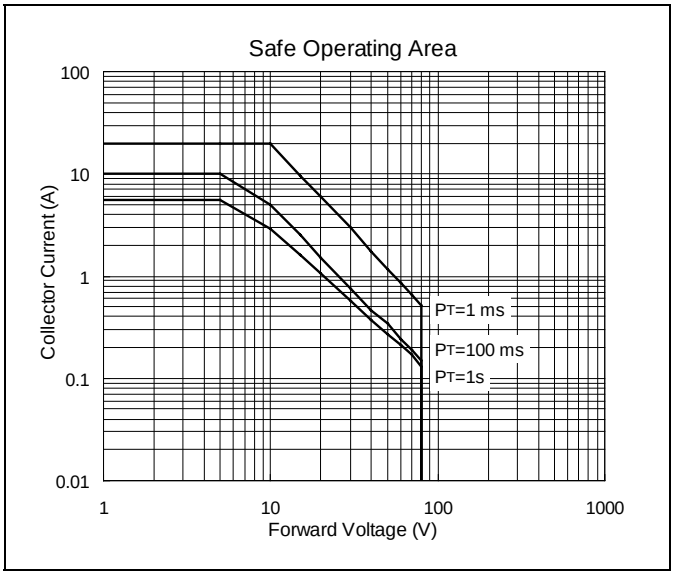
Characteristics Curve



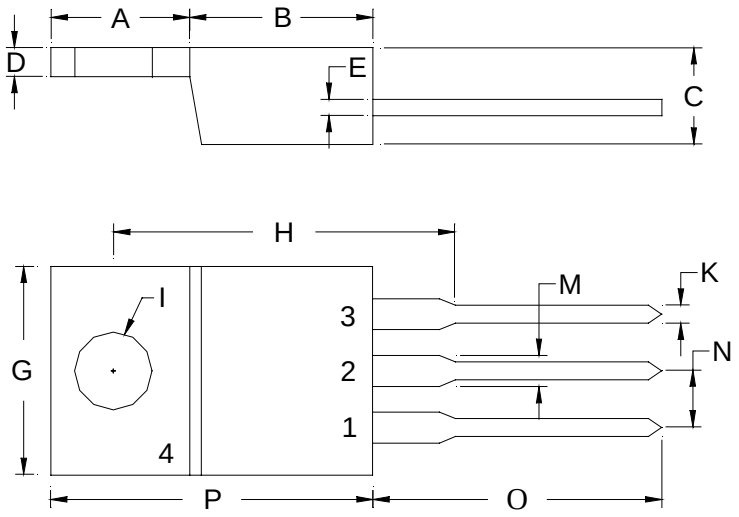




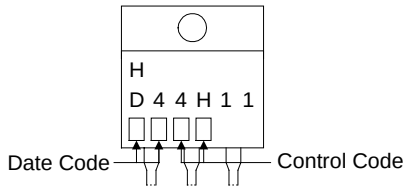




TO-220AB Dimension



Marking:



Style: Pin 1.Base 2.Collector 3.Emitter

3-Lead TO-220AB Plastic Package
HSMC Package Code: E

*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.2197	0.2949	5.58	7.49	I	-	*0.1508	-	*3.83
B	0.3299	0.3504	8.38	8.90	K	0.0295	0.0374	0.75	0.95
C	0.1732	0.185	4.40	4.70	M	0.0449	0.0551	1.14	1.40
D	0.0453	0.0547	1.15	1.39	N	-	*0.1000	-	*2.54
E	0.0138	0.0236	0.35	0.60	O	0.5000	0.5618	12.70	14.27
G	0.3803	0.4047	9.66	10.28	P	0.5701	0.6248	14.48	15.87
H	-	*0.6398	-	*16.25					

Notes: 1.Dimension and tolerance based on our Spec. dated Sep. 07,1997.
2.Controlling dimension: millimeters.
3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material:

- Lead: 42 Alloy; solder plating
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

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